



# CCFW56A75S

CHONG QING CLOUDCHILD TECHNOLOGY CO.,LTD

## FRD Chip for Automotive Applications

Quality Requirement Category:Automotive

### Features:

- Soft,fast switching
- Short reverse recovery time
- Low reverse recovery charge
- Positive temperature coefficient

### Applications:

- Motor drive
- SMPS
- UPS



Chip Type	$V_{RRM}$	$I_F$	Die Size	Package
CCFW56A75S	750V	225A	10×5.55 mm <sup>2</sup>	wafer

### Mechanical Parameters

Die size		10×5.55	mm <sup>2</sup>
Anode pad size		9.25×4.8	
Thickness		250	μm
Scribe line		100×100	μm
Wafer size		150	mm
Max.possible chips per wafer		257	
Anode metal		4μm AlSiCu	
Cathode metal		2.3μm Ti/Ni/Ag	
Storage environment	For original and sealed MBB bags	Humidity ≤25%RH, Temperature 18°C to 25°C, ≤6 months	

### Maximum Ratings

Parameter	Symbol	Value	Unit
Repetitive peak reverse voltage	$V_{RRM}$	750	V
Continuous forward current	$I_F$	225 <sup>1)</sup>	A
Maximum repetitive forward current	$I_{FRM}$	450	A
Operating junction temperature	$T_j$	-55 to +150	°C

<sup>1)</sup> depending on thermal properties of assembly

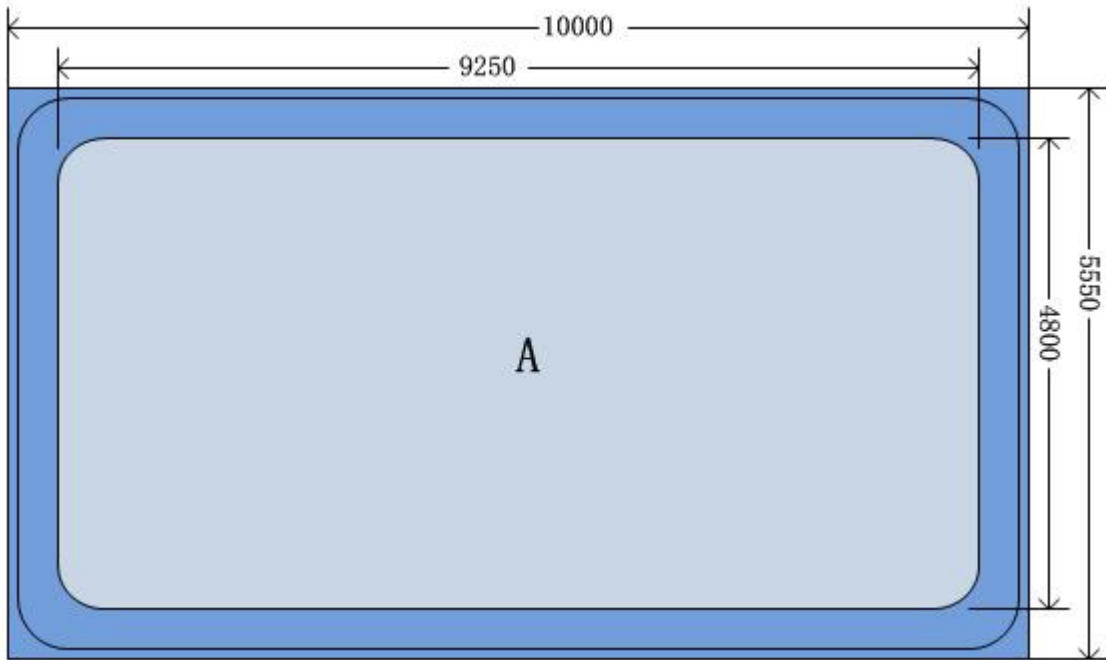


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Static Characteristics (tested on chip),  $T_j = 25^\circ\text{C}$

Parameter	Symbol	Conditions	Value			Unit
			min.	typ.	max.	
Breakdown voltage	$V_{(BR)}$	$I_R=1\text{mA}$	750			V
Reverse current	$I_R$	$V_R=750\text{V}$			100	$\mu\text{A}$
Forward voltage	$V_F$	$I_F=225\text{A}$	25 $^\circ\text{C}$	1.5	1.8	V
			150 $^\circ\text{C}$	1.52		

Chip Drawing (Unit: $\mu\text{m}$ )





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Date of change	Rev #	revise content
2022/8/22	A/0	/